

### **Wave Soldering**

Due to variances in equipment, solder, flux, and board design, Samtec does not recommend specific wave solder profiles for our connectors. The processing parameters provided by the flux manufacturer should be employed and can usually be found on their website.

For a lead-free wave process, the pot temperature (~260-270C) and contact time (~4 seconds) will likely be similar for most solders and fluxes, however different fluxes can require substantially different pre-heat temperatures.

For a tin-lead wave process, a pot temperature in the range of 230-250C and contact time of ~4 seconds is typically recommended.

Samtec strongly recommends a thorough thermal profile study be performed to fully understand the dynamics of your overall application.

For further discussion, please contact Samtec's Interconnect Processing Group (IPG) at [ipg@samtec.com](mailto:ipg@samtec.com) or 1-800-726-8329.